

File E181974
Project 07CA02022

March 16, 2007

REPORT

on

COMPONENT - NON-OPTICAL ISOLATING DEVICES

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TUCSON AZ 85706

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MODEL AMC1200

General - Model AMC1200 is representative of models, AMC1100, AMC1200B, AMC1200P, AMC1203, AMC1203B, AMC1204, AMC1204B, except as noted below.

1. Encoder - FET circuit.

Non-optical isolator model	Chip model
AMC1100, AMC1200, AMC1200B, AMC1200P	6AMC1200FNP
AMC1203, AMC1203B	6ICC03793EDS
AMC1204, AMC1204B	6ICC05234CDS

2. Decoder - FET circuit.

Non-optical isolator model	Chip model
AMC1100, AMC1200, AMC1200B, AMC1200P	CAMC1200AANP
AMC1203, AMC1203B	BLBFIS1203RAC
AMC1204, AMC1204B	CAMC1204AANP

3. Case - Epoxy Molding Resin, R/C (QMFZ2), type EME-G700HA by Sumitomo Bakelite (E41429). Molded using a high temperature and high-pressure process.

4. Lead Frame - Metal employed shall be of stainless steel, plated steel, copper, silver, gold, nickel, aluminum, an alloy of the same, or an equivalent material.

5. Wire (internal) - Gold.

6. Isolation Capacitor - The isolation barrier is provided through 0.008 mm of silicone dioxide between the capacitor plates. This device is located within the Decoder chip, item 2.

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